



BRP100N245P6

N-channel Enhancement Mode Power MOSFET

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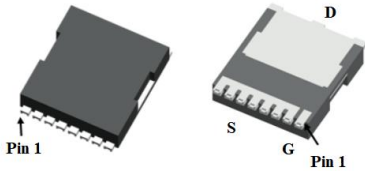
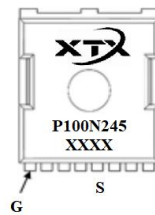
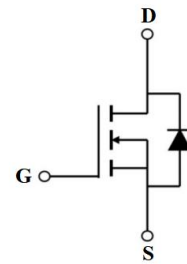
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FEATURES

- ◆ 100V, 245A
- ◆ $R_{DS(ON)} < 1.2m\Omega @ V_{GS} = 10V$
- ◆ Ultra-low $R_{DS(ON)}$
- ◆ Low Gate Charge
- ◆ Lead Free

APPLICATIONS

- ◆ Motor Driving in Power Tool, E-vehicle, Robotics
- ◆ Current Switching in DC/DC & AC/DC
- ◆ Power Management


TOLL-8

Marking and Pin Assignment

Schematic Diagram

PACKAGE MARKING AND ORDERING INFORMATION

OPN	Marking	Package	Quantity
BRP100N245P6	P100N245 XXXX	TOLL-8	2000pcs/Reel

ABSOLUTE MAXIMUM RATINGS

Symbol	Definition	Ratings	Unit	
V_{DS}	Drain-to-Source Voltage	100	V	
V_{GS}	Gate-to-Source Voltage	± 20	V	
I_D	Continuous Drain Current	$T_C = 25^\circ C$	245	A
		$T_C = 100^\circ C$	175	A
I_{DM}	Pulsed Drain Current ⁽¹⁾	980	A	
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	1488	mJ	
P_D	Power Dissipation, $T_C = 25^\circ C$	465	W	
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.27	$^\circ C/W$	
T_J, T_{STG}	Junction & Storage Temperature Range	-55 ~ +150	$^\circ C$	

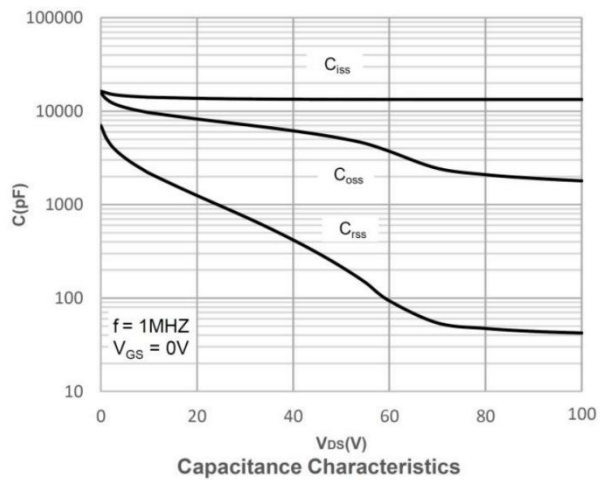
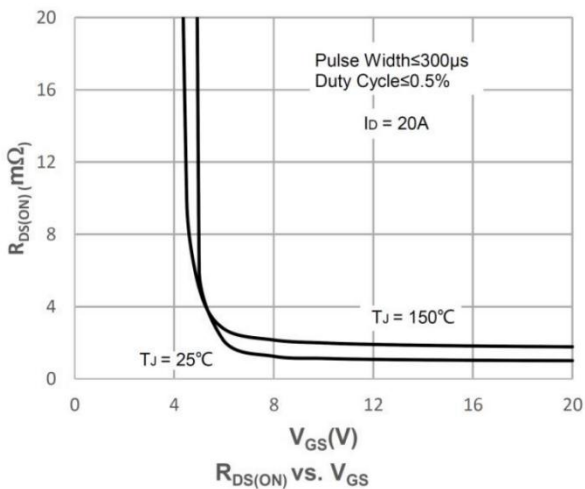
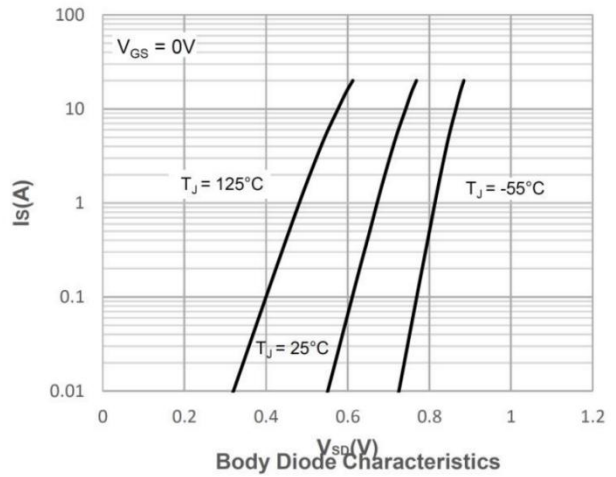
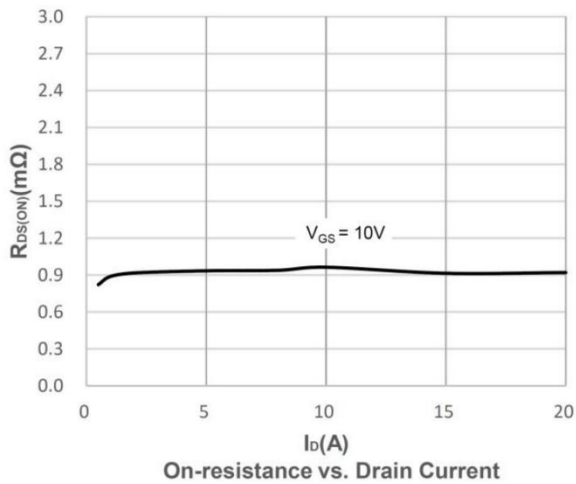
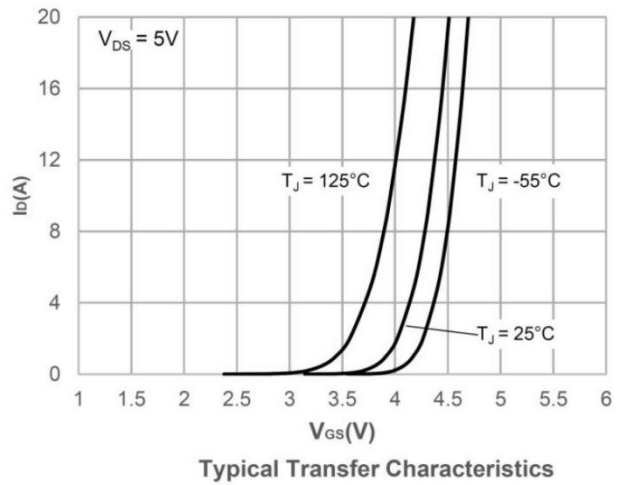
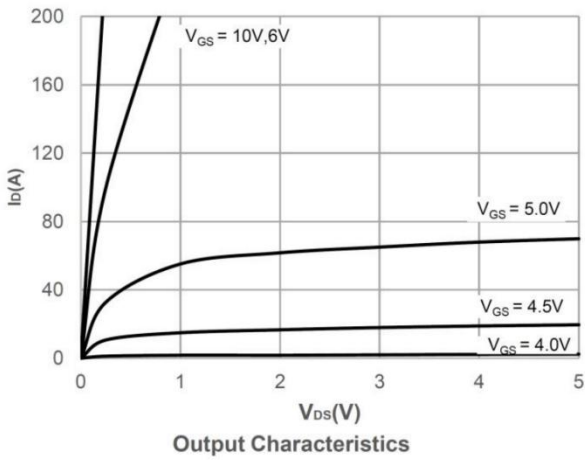
ELECTRICAL CHARACTERISTICS (All test condition is $T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}$	-	-	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0	3.0	4.0	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 10\text{V}, I_D = 20\text{A}$		1.0	1.2	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 50\text{V},$ $f = 1\text{MHz}$	13731	13883	14678	pF
C_{oss}	Output Capacitance		7784	8005	8209	pF
C_{rss}	Reverse Transfer Capacitance		593	722	888	pF
R_g	Gate Resistance	$V_{GS} = 0\text{V}, V_{DS} = 0\text{V},$ $f = 1\text{MHz}$	-	4.3	-	Ω
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ to } 10\text{V}$ $V_{DS} = 50\text{V}, I_D = 20\text{A}$	-	218	-	nC
Q_{gs}	Gate Source Charge		-	66	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	57	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{GS} = 10\text{V}, V_{DS} = 50\text{V}$ $I_D = 20\text{A}, R_{GEN} = 1.6\Omega$	-	43	-	ns
t_r	Turn-On Rise Time		-	71	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	149	-	ns
t_f	Turn-Off Fall Time		-	89	-	ns
Drain-Source Diode Characteristics						
I_S	Continuous Source Current		-	-	245	A
V_{SD}	Forward on voltage	$V_{GS} = 0\text{V}, I_S = 1\text{A}$	-	-	1.2	V
T_{rr}	Reverse Recovery Time	$I_F = 20\text{A}, di/dt = 100\text{A}/\mu\text{s}$	-	136	-	ns
Q_{rr}	Reverse Recovery Charge		-	380	-	nC

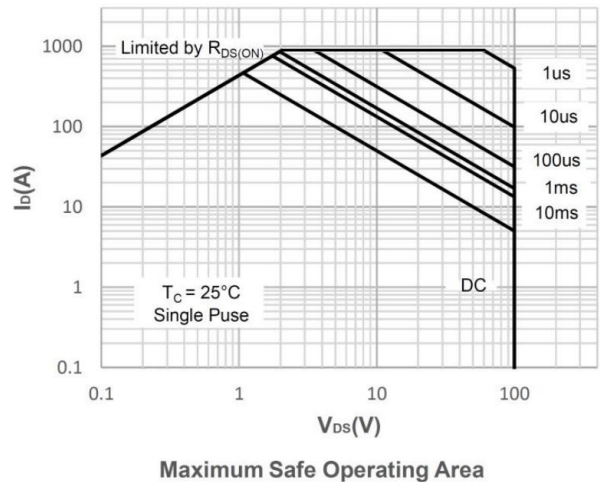
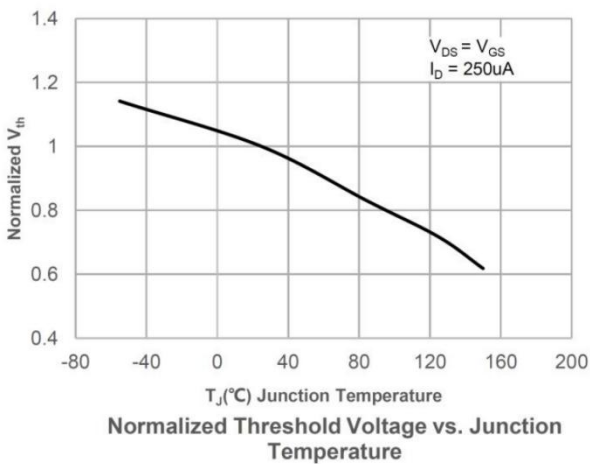
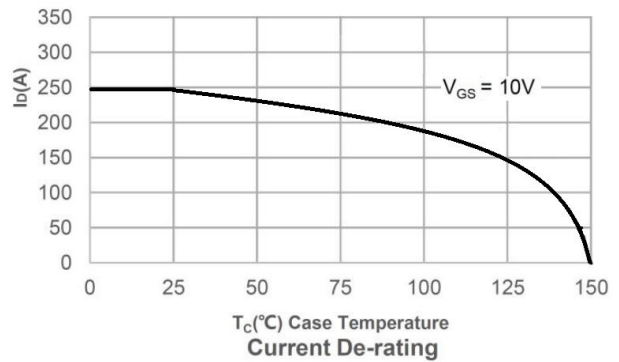
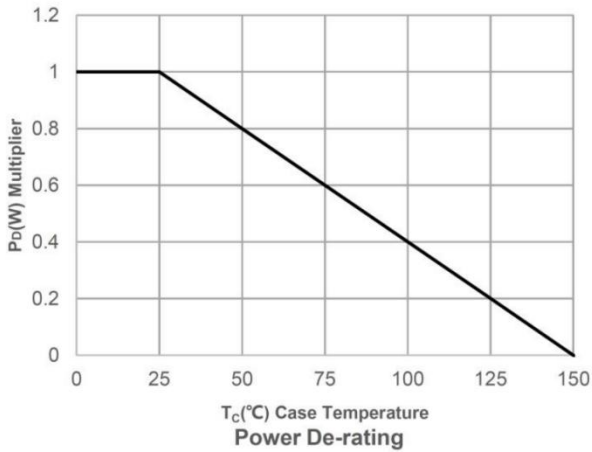
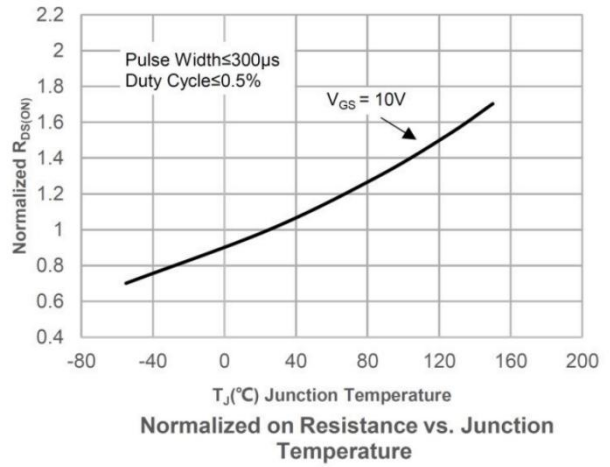
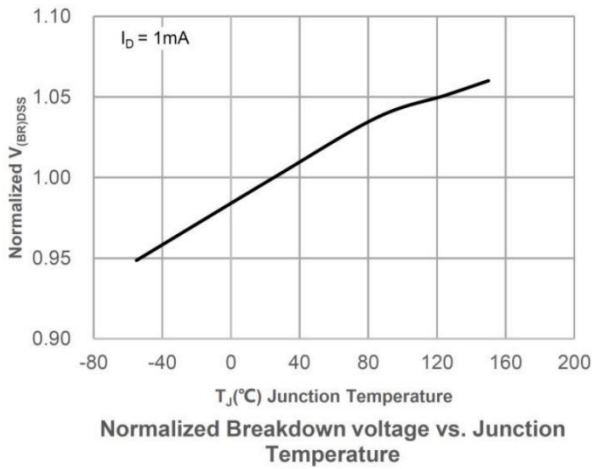
Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E_{AS} condition: Starting $T_J=25^{\circ}\text{C}$, $V_{DD}=50\text{V}$, $V_G=10\text{V}$, $L=3\text{mH}$, $I_{AS}=31.5\text{A}$
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

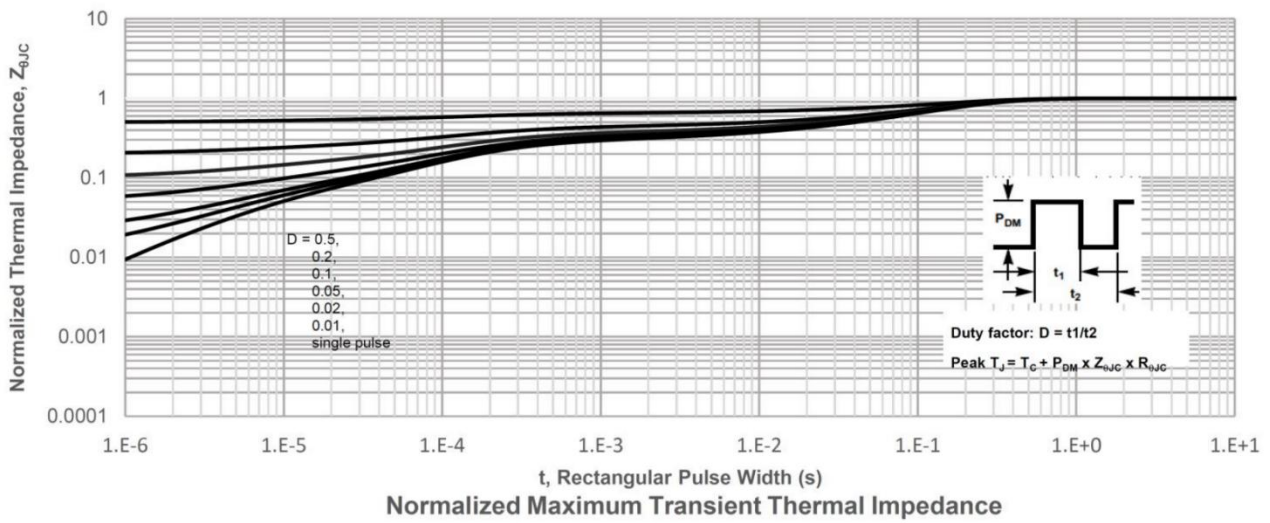
TYPICAL PERFORMANCE CHARACTERISTICS



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TEST CIRCUIT

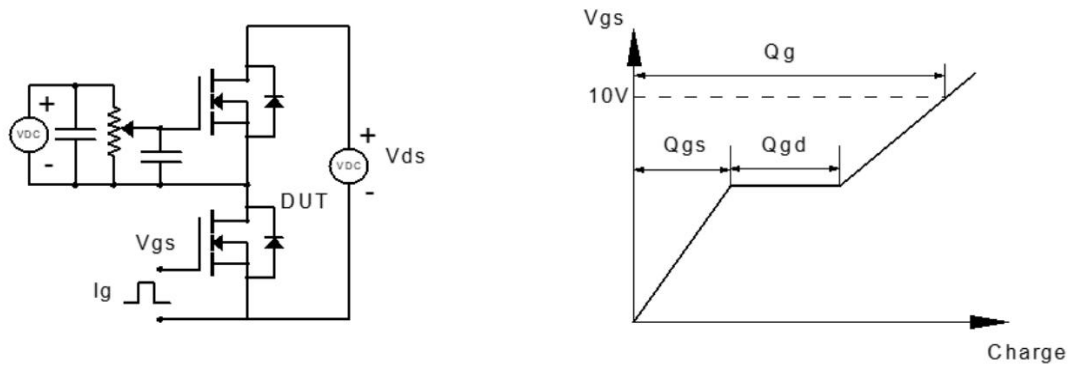


Figure 1: Gate Charge Test Circuit & Waveform

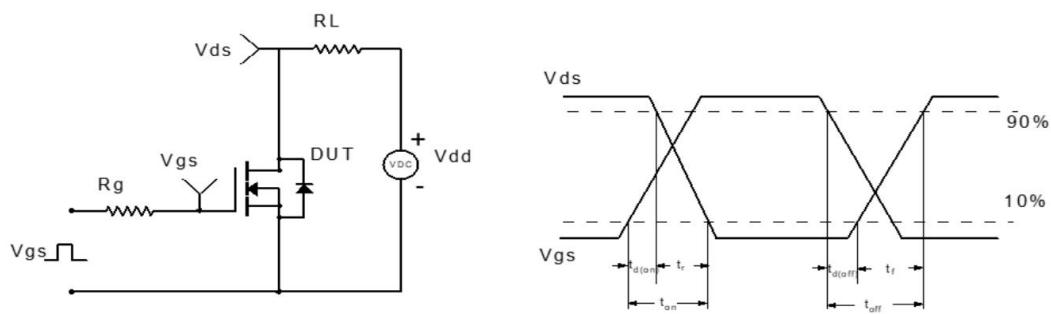


Figure 2: Resistive Switching Test Circuit & Waveform

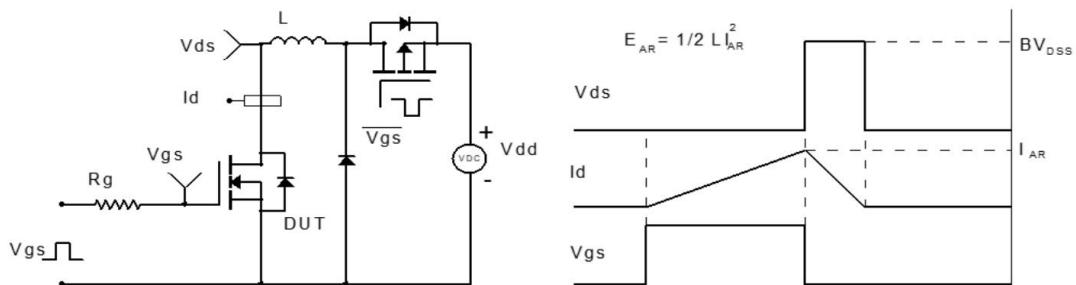


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

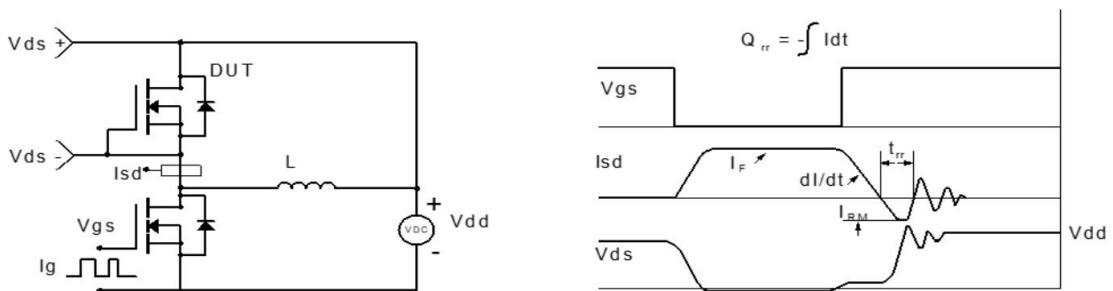
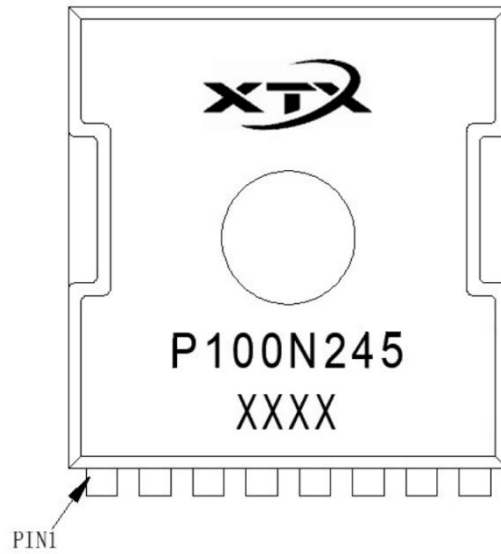


Figure 4: Diode Recovery Test Circuit & Waveform

MARKING INFORMATION



1st Line: XTX Logo

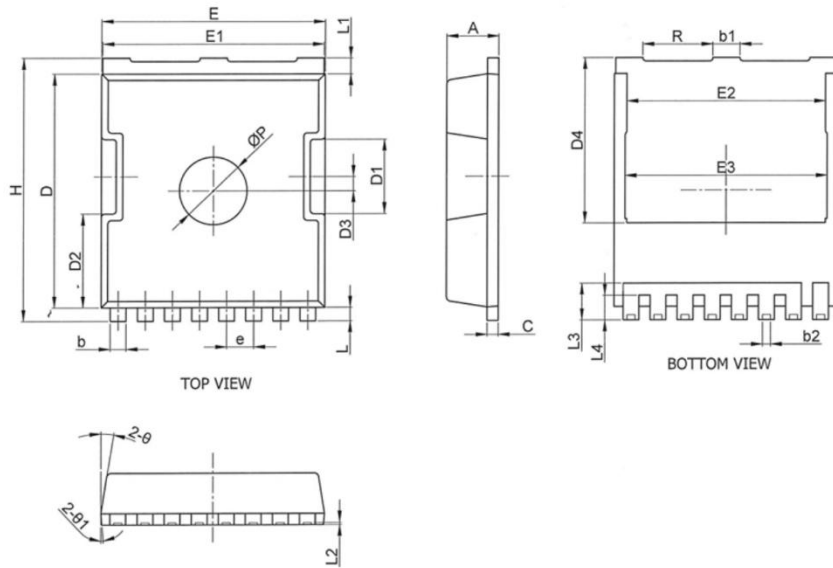
2nd Line: Part Number (P100N245)

3rd Line: Date Code (XXXX)

XX: Year

XX: Week (01 to 53)

Year	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033
Code	21	22	23	24	25	26	27	28	29	30	31	32	33

DETAIL PACKAGE OUTLINE DRAWING (TOLL-8)


SYMBOL	MILLIMETERS		
	MIN	NOM	MAX
A	2.20	2.30	2.40
b	0.60	0.70	0.80
b1	1.10	1.20	1.30
b2	0.26	0.36	0.51
C	0.40	0.50	0.60
D	10.30	10.40	10.50
D1	3.20	3.30	3.40
D2	4.08	4.18	4.28
D3	0.53	0.63	0.73
D4	7.25	7.35	7.50
E	9.80	9.90	10.00
E1	9.70	9.80	9.90
E2	8.70	8.80	8.90
E3	8.85	8.95	9.05
e	1.20 BSC		
H	11.50	11.70	11.90
L	0.50	0.60	0.70
L1	0.60	0.70	0.80
L2	0.05	0.10	0.20
L3	1.45	1.65	1.85
L4	0.90	1.10	1.30
P	2.00	3.00	4.00
R	3.00	3.10	3.20
θ	7°	9°	11°
θ_1	3°	5°	7°

REVISION HISTORY

Number	Description
Rev 1.0	BRP100N245P6 datasheet release